

## AMENDMENTS TO THE SPECIFICATION

Please amend the title as follows:

Semiconductor Component Having Thinned Die  
~~Encapsulated By~~ With Contact Bumps And Polymer Layers On  
Six Surfaces Sides

On page 2, line 1, in the "Cross Reference To Related Applications" added by the Preliminary Amendment dated August 21, 2003, please make the following changes.

### Cross Reference To Related Applications

This application is a division of serial no. 10/094,161, filed 03/06/2002, Patent No. 6,908,784.

This application is related to serial no. 10/646,897, filed 08/21/2003, to serial no. 10/719,876, filed 11/21/03, Patent No. 6,964,915, to serial no. 11/052,279, filed 02/07/05, to serial no. 11/050,857, filed 02/07/05, and to serial no. 11/146,397 filed 06/06/2005.